



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



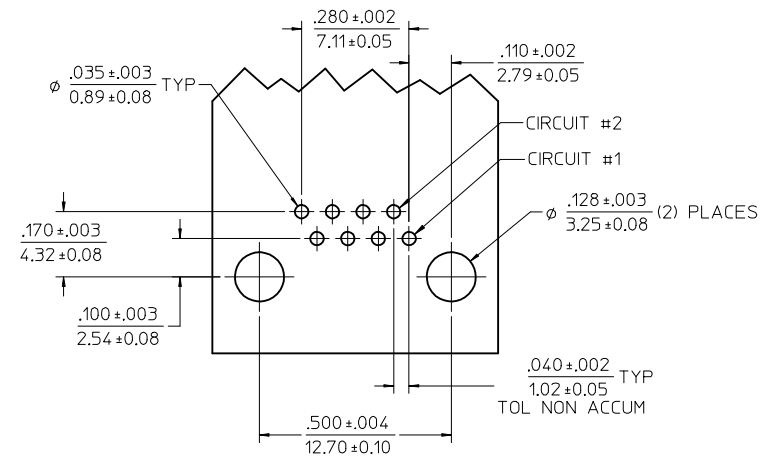
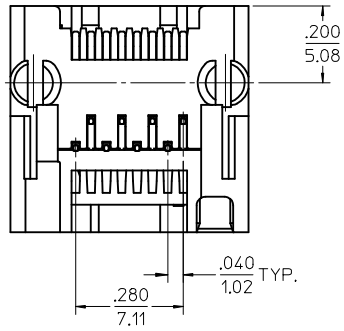
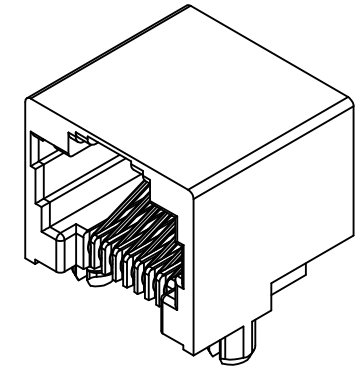
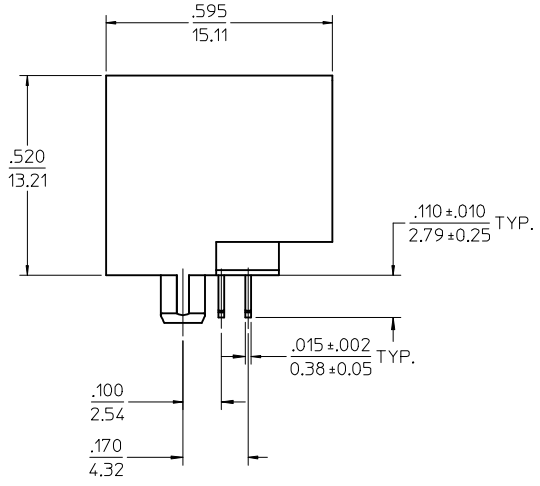
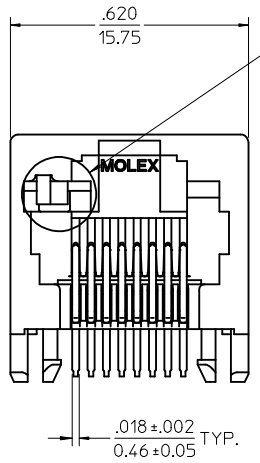
Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

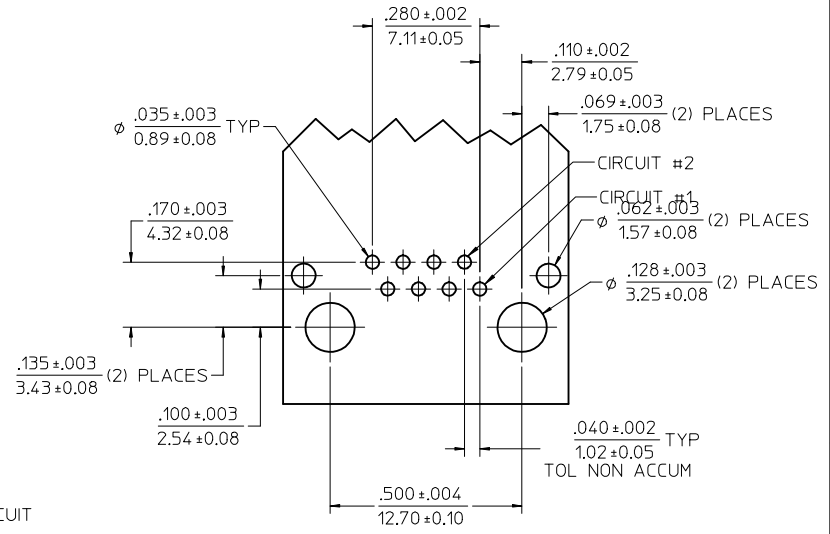
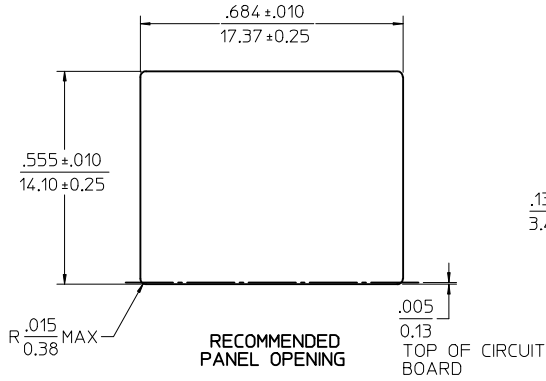
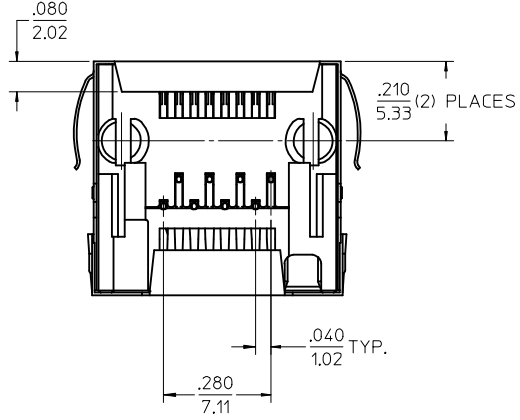
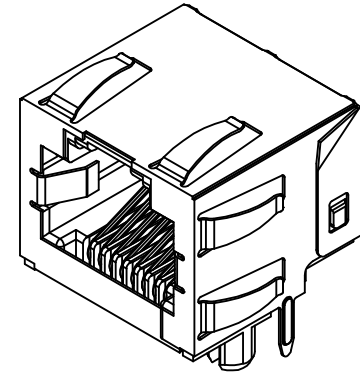
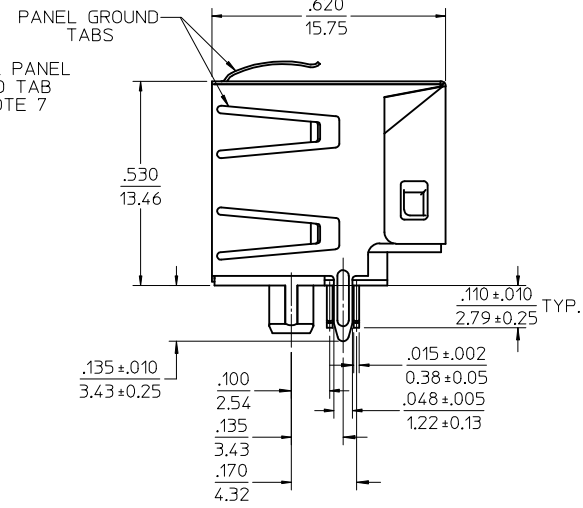
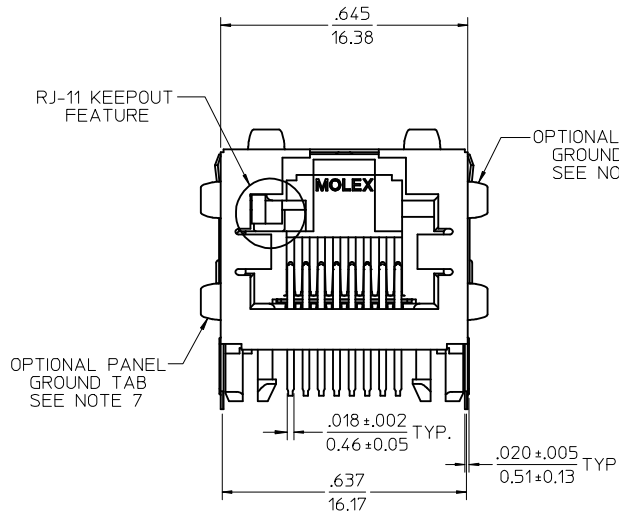




PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

- NOTES:
- 1) MATERIAL:
HOUSING: NYLON(IPA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
 - 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 - 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX
PACKAGING SPECIFICATION PK-43860-004.
 - 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

UPDATE VIEWS IEC NO: UCP2015-0148 2014/08/22 DRWINHNGUYEN 2014/08/22 CHKD:JBELL 2015/05/19 APPR:FSMITH	DESCRIPTION REV#	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		▽=0	mm INCH	IN/MM	4:1	INCH	RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE molex DOCUMENT NO. SD-44620-001 SHEET NO. 1 OF 4
		▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
		▽=0	3 PLACES ± --- ± ---	MKAMAR 00/03/07			
▽=0	2 PLACES ± --- ± ---	CHECKED BY DATE					
		1 PLACE ± --- ± ---	MKAMAR 00/03/07				
		0 PLACE ± --- ± ---	APPROVED BY DATE				
			JROBERTS 00/03/07				
			MATERIAL NO.				
			446200001				
			ANGULAR ±1/2°				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE			
				C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

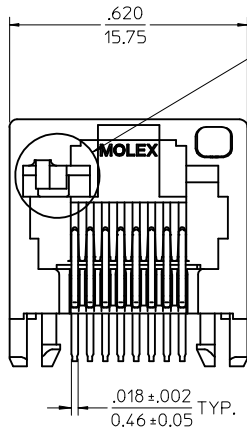


PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

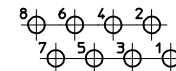
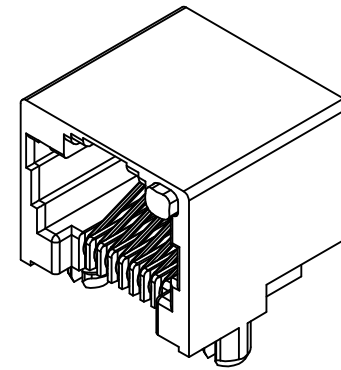
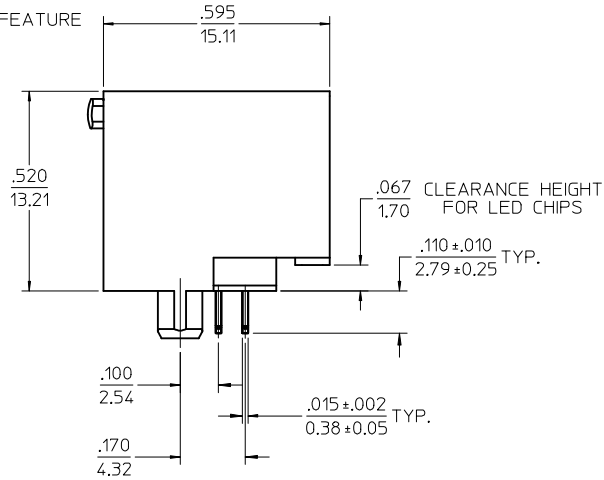
- NOTES:
 1) MATERIAL:
 HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
 TERMINALS: PHOSPHOR BRONZE
 SHIELD: BRASS
 2) FINISH:
 TERMINALS:
 SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
 SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 SHIELD:
 100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
 (1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 4) PACKAGING SPECIFICATION:
 CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX
 PACKAGING SPECIFICATION PK-43860-005.
 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR
 SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
 SPECIFICATION PS-45499-002.

ASSEMBLY MATERIAL NUMBER	PANEL GROUND TABS
446200002	ALL
446200003	SEE NOTE 7

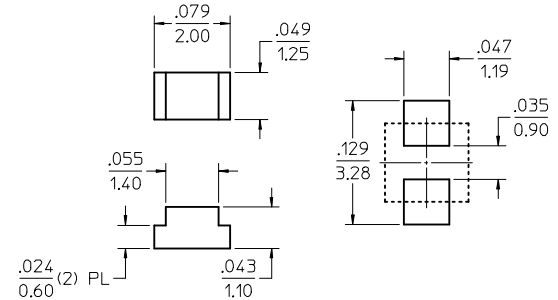
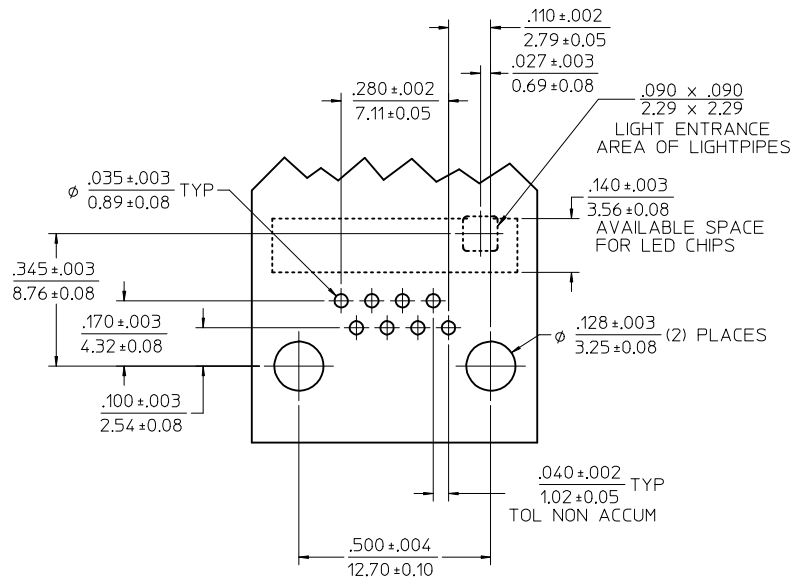
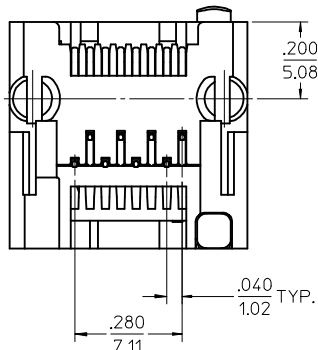
SEE SHEET 1 EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/08/22 CHKD: JEBEL 2014/08/22 APPR: FSMITH 2015/05/19	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± --- ± ---	1 PLACE ± --- ± ---	0 PLACE ± ±	DRAWN BY MKAMAR 00/03/07		
		ANGULAR ±1/2°		MATERIAL NO. SEE CHART		DATE 00/03/07		TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEP-OUT FEATURE	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		DATE 00/03/07		DOCUMENT NO. SD-44620-001	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								SHEET NO. 2 OF 4	



RJ-11 KEEPOUT FEATURE



TYPICAL PC TERMINAL HOLE LAYOUT
SCALE 5:1



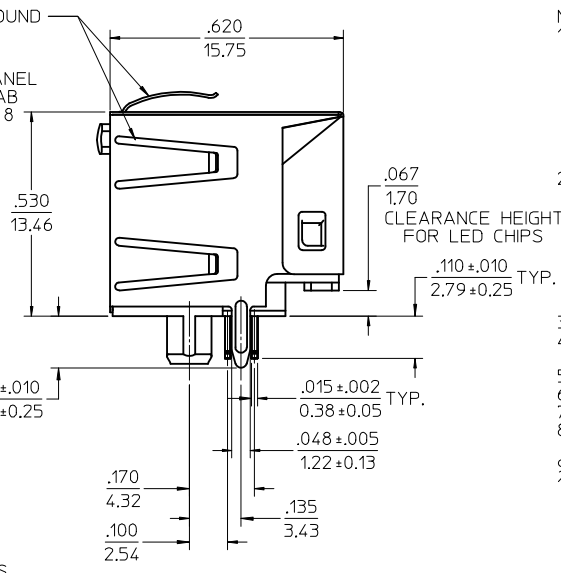
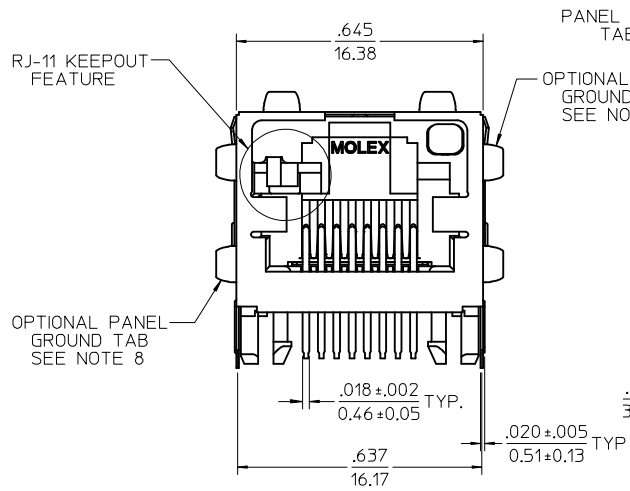
RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 10:1
(SEE NOTE 8)

PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

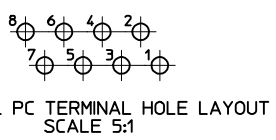
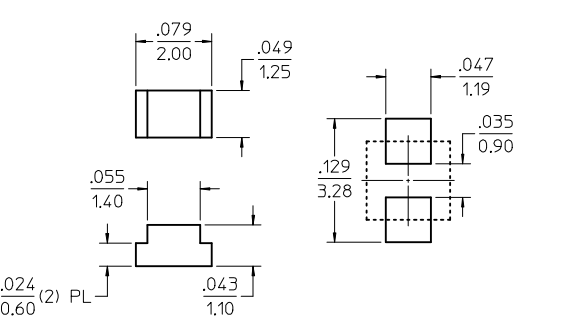
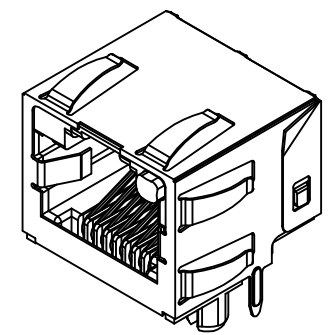
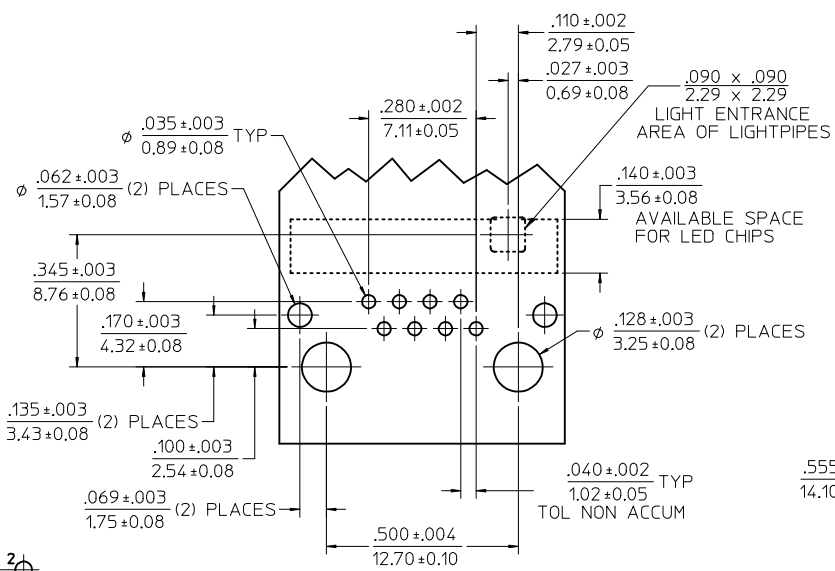
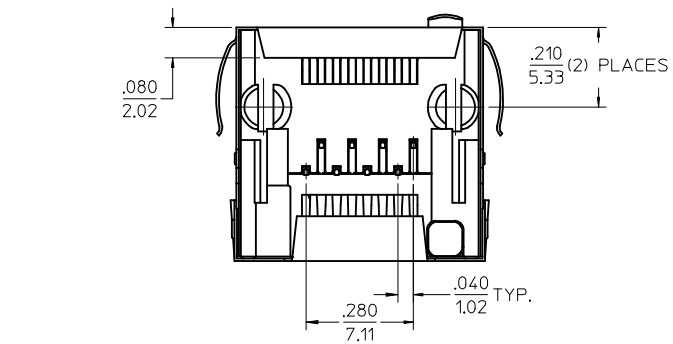
- NOTES:
 1) MATERIAL:
 HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
 TERMINALS: PHOSPHOR BRONZE
 LIGHT PIPES:
 POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
 POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 2) FINISH:
 TERMINALS:
 SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
 SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 4) PACKAGING SPECIFICATION:
 CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX PACKAGING SPECIFICATION PK-43860-004.
 5) APPLICATION SPECIFICATION: AS-43860-001.
 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 8) FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

ASSEMBLY MATERIAL NUMBER	LIGHT PIPE MATERIAL
446201004	POLYCARBONATE
446201005	POLYSULFONE

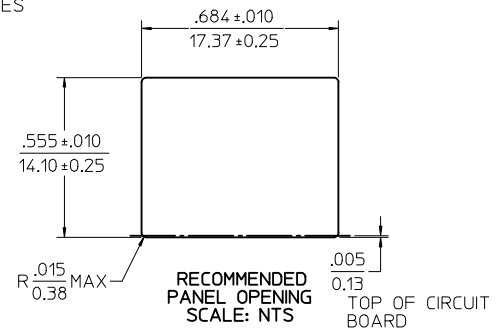
SEE SHEET 1 EC NO: UCP2015-0148 DR: WANGUYEN 2014/08/22 CHKD: JEBELL 2014/08/22 APPR: FSMITH 2015/05/19 D3	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± --- ± ---	1 PLACE ± --- ± ---	0 PLACE ± --- ± ---	DRAWN BY MKAMAR	DATE 00/03/07	TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE
		ANGULAR ±1/2°		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-44620-001		SHEET NO. 3 OF 4	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



- NOTES:
- MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
LIGHT PIPES:
POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICRONS (1.27 MICROMETERS) MIN., SELECT TIN IN PC TAIL AREA: 100 MICRONS (2.54 MICROMETERS) MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICRONS (1.27 MICROMETERS) MIN.
SHIELD:
100 MICRONS (2.54 MICROMETERS) NICKEL OVER 50 MICRONS (1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
 - PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - PACKAGING SPECIFICATION: CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
 - APPLICATION SPECIFICATION: AS-43860-001
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 10:1
(SEE NOTE 9)

TYPICAL PC TERMINAL HOLE LAYOUT
SCALE 5:1

RECOMMENDED
PANEL OPENING
SCALE: NTS
TOP OF CIRCUIT BOARD

ASSEMBLY MATERIAL NUMBER	LIGHT PIPE MATERIAL	PANEL GROUND TABS
446201006	POLYCARBONATE	ALL
446201007	POLYCARBONATE	SEE NOTE 8
446201008	POLYSULFONE	ALL
446201009	POLYSULFONE	SEE NOTE 8

SEE SHEET 1	QUALITY SYMBOLS
EC NO: UCP2015-0148	▽=0
DRW: NGUYEN	▽=0
CHKD: JEBELL	▽=0
APP: FSMITH	
REV	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ±	±
3 PLACES ±	±
2 PLACES ±	±
1 PLACE ±	±
0 PLACE ±	±
ANGULAR ±1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
IN/MM	
DRAWN BY	DATE
DATE	00/03/07
CHECKED BY	DATE
DATE	00/03/07
APPROVED BY	DATE
DATE	00/03/07
MATERIAL NO.	
SEE CHART	
SIZE	C

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
4:1	INCH	
RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE		
molex		
DOCUMENT NO.	SD-44620-001	SHEET NO. 4 OF 4
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		